# Product End-of-Life Disassembly Instructions

## Product Category: External Options

### Marketing Name / Model

[List multiple models if applicable.]

**HP RP9 G1 AiO Retail System, Model 9118**

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries Battery pack;RTC</td>
<td>1</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by <em>(check all that apply with an “x” inside the “[]”):</em> [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain _______ NOtE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords DC Cable for External Power Supply</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](#)
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0
Components and waste containing asbestos | | 0
Components, parts and materials containing refractory ceramic fibers | | 0
Components, parts and materials containing radioactive substances | | 0

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philips Screwdriver</td>
<td>T15 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Slotted Screwdriver</td>
<td>2# 2.55-3.00kgf.cm</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Removed the base by loosening the latch.
2. Tore off the label of the case.
3. Pried open the case.
4. Removed the plastic frame.
5. Removed the metal sheet and tape of the plastic frame.
7. Removed the plastic case.
8. Removed the metal parts of the case.
9. Removed the metal frame.
10. Removed the metal frame by loosening 5 screws.
11. Removed the fan by loosening 3 screws.
12. Removed the metal frame for HDD by loosening 2 screws.
13. Removed the plastic parts of the metal frame by loosening 4 screws.
14. Removed the button cell.
15. Removed the side of PCB assembly by loosening 3 screws.
16. Removed the cable of the PCB assembly.
17. Removed the speaker.
18. Removed the antenna by loosened 2 screws.
19. Tore off sticker of the metal frame.
20. Loosened 9 screws of the PCB assembly.
21. Removed the PCB assembly.

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*HPI instructions for this template are available at [EL-MF877-01]*
22. Tore off the thermal pad of the metal frame.
23. Loosened 18 screws of the metal frame.
24. Removed the metal frame.
25. Separated the PCB assembly and plastic frame by removing cable.
26. Tore off the tape of LCD.
27. Removed the plastic frame of the panel.
28. Separated the touch panel and LCD.
29. Removed the FPC of the touch panel.
30. Removed the latch of the base by loosening 4 screws.
31. Removed the bracket of base by loosening 4 screws.
32. Separated the metal and plastic frame of the base-bracket.
33. Removed the plastic component of the joint part by loosening 2 screws.
34. Removed the tip pad by loosening 4 screws.
35. Opened the bottom cover by loosening 1 screw.
36. Tore off the thermal pad of the base.
37. Removed the side cover of the base.
38. Separated the base and stander by loosening 10 screws.
39. Pried open the plastic case of the joint parts.
40. Completed disassembly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Removed the base by loosening the latch.

Loosened 10 screws of the case.

Removed the plastic case.

Removed the metal frame for HDD by loosening 2 screws.

Tore off the label of the case.

Removed the metal sheet and tape of the plastic frame.

Removed the metal parts of the case.

Removed the fan by loosening 3 screws.

Pried open the case.

Pried open the case.

Removed the plastic frame.

Removed the metal frame.

Removed the metal frame by loosening 5 screws.
Removed the plastic parts of the metal frame by loosening 4 screws.

移開4顆螺絲以移除塑膠鐵框上的固定件。

Removed the heat sink by loosening 3 screws.

移開3顆螺絲以移除散熱片。

Tore off the tapes of the heat sink.

撕除散熱片上的膠帶。

Removed the cable of the PCB assembly.

移除電路板上的電線。

Removed the side of PCB assembly by loosening 3 screws.

移開3顆螺絲以移除側邊電路板。

Removed the button cell.

移除鈕扣電池。（S.S.T.）

Removed the speaker.

移除喇叭。

Tore off sticker of the metal frame.

撕除金屬框上的貼紙。

Loosened 9 screws of the PCB assembly.

鬆開電路板上的9顆螺絲。

Removed the PCB assembly.

移除電路板。（S.S.T.）

Loosened 18 screws of the metal frame.

鬆開18顆內框的螺絲。

Tore off the thermal pad of the metal frame.

撕除金屬框的散熱貼紙。
Removed the metal frame.
移除金属框。

Separated the touch panel and LCD.
分離觸控面板與 LCD。

Removed the antenna by loosened 2 screws.
輕開 2 鋼絲以移除天線。

Removed the PCB assembly of the plastic frame.
移除塑膠框上的電路板。

Removed the plastic frame of the panel.
移除面板的塑膠框。

Tore off the tape of LCD.
撕除 LCD 上的膠帶。

Removed the FPC of the touch panel.
分離觸控面板上的 FPC。

Removed the latch of the base by loosening 4 screws.
輕開 4 鋼絲以移除底座上的卡榫。

Removed the bracket of base by loosening 4 screws.
輕開 4 鋼絲以移除底座上的托架。

Removed the tip pad by loosening 4 screws.
輕開 4 鋼絲以移除底座上的支腳。

Removed the plastic component of the joint part.
移除接合部位的塑膠件。

Separated the metal and plastic frame of the base.
分離支架上的塑膠殼。

Separated the base and stander by loosening 10 screws.
輕開 10 鋼絲以分離底座與支樑。

Pried open the plastic case of the joint parts.
撬開支架上的塑膠殼。

Completed disassembly.
完成拆解。

HPI instructions for this template are available at EL-MF877-01